Abstracts

Characteristic Impedance of Integrated Circuit Bond Wires (Short Papers)

R.H. Caverly. "Characteristic Impedance of Integrated Circuit Bond Wires (Short Papers)." 1986 Transactions on Microwave Theory and Techniques 34.9 (Sep. 1986 [T-MTT]): 982-984.

In microwave circuit analysis, bond wires are frequently modeled as lumped elements or sections of microstrip. These models are insufficient since part of the wire is suspended above the substrate. This paper shows numerical results that provide the line impedance and effective dielectric constant for a round wire above a grounded dielectric substrate.

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